EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("20030080398").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/26 01:02
L2	1691	(@ad<"20030930") and 438/106. ccls. and (csp or (chip adje scale))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:04
L3	1	("20030080398").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/26 01:04
L4	362	(@ad<"20030930") and 438/106. ccls. and (csp or ((wafer or chip) adj scale))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:29
L5	271	L4 and (remove or removal or pull or etch or etching or cmp or polish)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:29
L6	1	("6693358").PN.	USPAT; USOCR	OR	OFF	2006/06/26 01:09
L7	1	("6326697").PN.	USPAT; USOCR	OR	OFF	2006/06/26 01:10
L8	1	("6781244").PN.	USPAT; USOCR	OR	OFF	2006/06/26 01:11
L9	1	("20030232488").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/26 01:12
L10	1	("6326689").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/26 01:13
L11	1	("6603191").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/26 01:14
L12	1	("20020038890").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/26 01:15

L13	10797	(@ad<"20030930") and (semiconductor or die or dice or "ic") and (csp or ((wafer or chip) adj scale))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:24
L14	5608	L13 and (remove or removal or pull or etch or etching or cmp or polish)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:26
L15	2588	L14 and (peripheral or periphery)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:25
L16	2733	L13 and ((remove or removal or pull or etch or etching or cmp or polish) with (wafer or substrate or glass or tape))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:27
L17	1684	L15 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:27
L18	1811	L16 not L17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:28
L19	1743	L18 not L5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:28
L20	4637	(@ad<"20030930") and "257"/$.ccls. and (csp or ((wafer or chip) adj scale))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:29

L21	3296	L20 and (remove or removal or pull or etch or etching or cmp or polish)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:30
L22	1577	L21 not L16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/26 01:30